



Printed Circuit Boards
Interconnection Carriers

PRINTED CIRCUIT BOARDS

01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

| a | b | c | d | e | f | g + h + i |
|---|---|---|---|---|---|-----------|
|---|---|---|---|---|---|-----------|

04 154 FR4 35 L108.35 P10_06

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_154_FR4_35_L108.35_p10_06

| Layers | in μ | Material | Build-Up | Assembly |
|----------|------------|----------|----------|----------|
| Layer-1 | 35 μ | Copper | | |
| | 60 μ | Prepreg | | |
| | 100 μ | Prepreg | | |
| Layer-2 | 35 μ | Copper | | |
| | 1080 μ | L-FR4 | | |
| Layer-3 | 35 μ | Copper | | |
| | 100 μ | Prepreg | | |
| | 60 μ | Prepreg | | |
| Layer-99 | 35 μ | Copper | | |